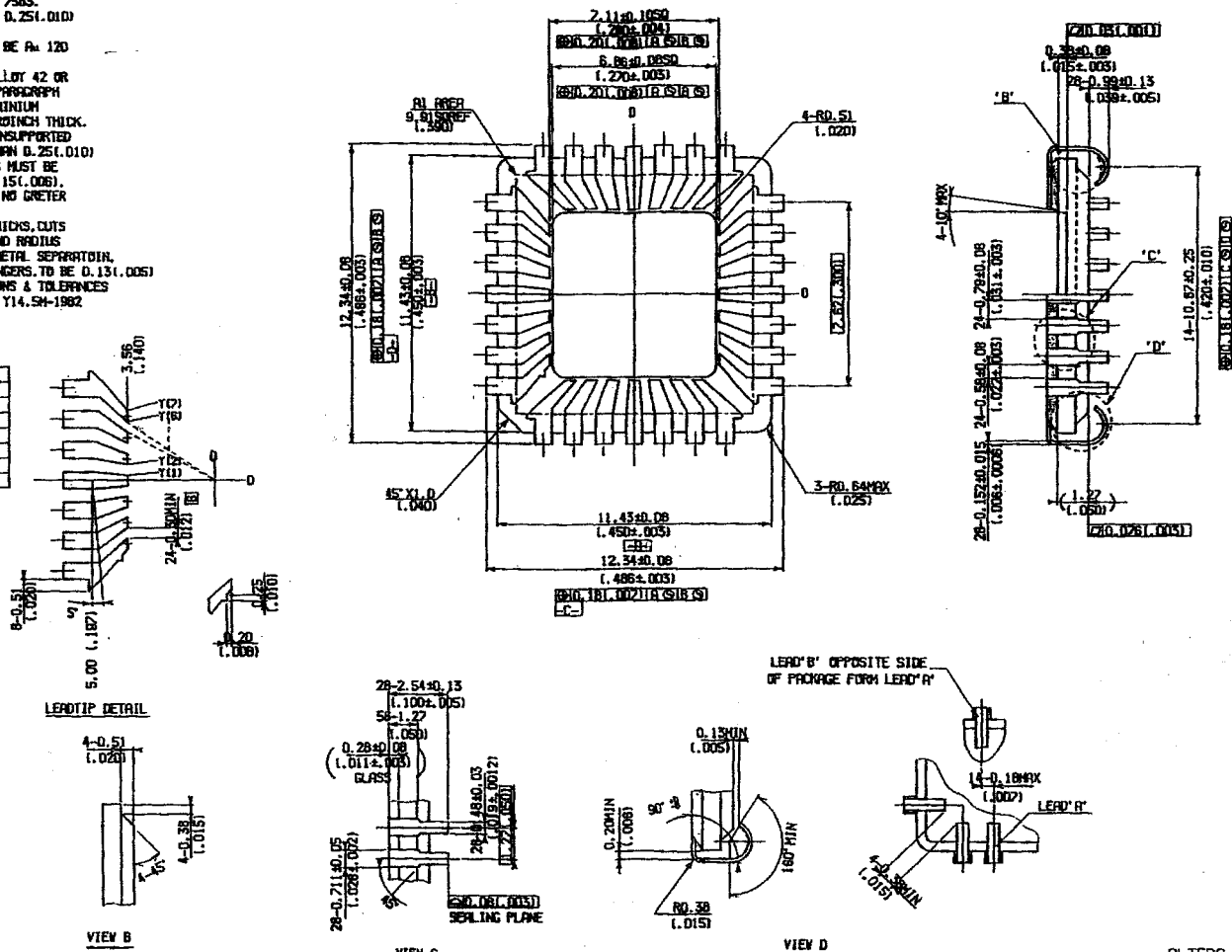


# SSM P/N CQJ02806

**NOTES**

1. MATERIALS  
 CERAMIC TO SPEC. 90-94Z Al<sub>2</sub>O<sub>3</sub>  
 SOLDER GLASS TO BE 7503.  
 MAX PULLBACK TO BE 0.25(010)  
 FROM CERAMIC EDGE.  
 DIE ATTACH AREA TO BE A<sub>1</sub> 120  
 MICROINCH MIN.  
 LEAD FRAME TO BE ALLOY 42 OR  
 TYPE B MIL 38510 PARAGRAPH  
 3.5.6.1. WITH ALUMINUM  
 BOND PADS 100 MICROINCH THICK.  
 2. THERE WILL BE NO UNSUPPORTED  
 BOND PADS GREATER THAN 0.25(010)  
 4. ADJACENT BOND PADS MUST BE  
 CO-PLANNER WITHIN 0.15(006).  
 TOTAL CO-PLANNRITY NO GREATER  
 THAN 0.25(010).  
 5. THERE WILL BE NO NICKS, CUTS  
 OR GLASS IN THE BOND RADIIUS  
 6. MINIMUM INTERNAL METAL SEPARATION,  
 OTHER THAN BOND FINGERS, TO BE 0.13(005)  
 7. INTERPRET DIMENSIONS & TOLERANCES  
 IN ACCORDANCE WITH Y14.5M-1982

NO.	YIN.
1	0.250(.0091)
2	0.580(.0230)
3	1.20(.0471)
4	1.550(.0610)
5	2.010(.0791)
6	2.440(.0961)
7	2.900(.1142)



ALTER TYPE

NAME ZBLD QUAD CERPAC J (450-270)	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DATE MAR 12
SCALE (8 X 11)	MATERIAL	CHECK
KYOCERA CORPORATION		QC-028240-J

